

BOA1330070YY300MXXXX

Fiber Coupled Booster Semiconductor Optical Amplifier



Features:

- High output power >300mW @ 1330nm
- High saturation output power (21dBm)
- Proprietary anti-reflection coating technology enabling high reliability
- Polarization maintaining PM1310 fiber or HI1060 fiber
- 900um loose tube on fiber (optional)

Applications:

- Swept sources, tunable lasers
- Optical coherence tomography (OCT)
- Silicon photonics and PIC characterization
- O-band optical test and measurement

Recommended Operating Conditions

@ CW, Tcase=25°C

Parameter	Min.	Typ.	Max.	Unit
Chip Temperature	20	25	40	°C
Forward Current		2000	3000	mA
Output Power in Amplification Mode			300	mW
Input Optical Power	-25	10	15	dBm

Gain Characteristics

@ CW, 25°C, 2000mA, with input signal 10dBm, 1330nm

Parameter	Min.	Typ.	Max.	Unit
Forward Current @ 300mW			3000	mA
Saturation Output Power @ -3dB	17	21		dBm
Gain	10	14		dB
Small Signal Gain @ Pin=-20dBm	20	24		dB
Peak Wavelength	1320	1330	1340	nm
Bandwidth @ -3dB		70		nm
Noise Figure @ 1A; Pin=-20dBm		7		dB

Amplified Spontaneous Emission (ASE) Characteristics

@ CW, 25°C, 2000mA, no input signal

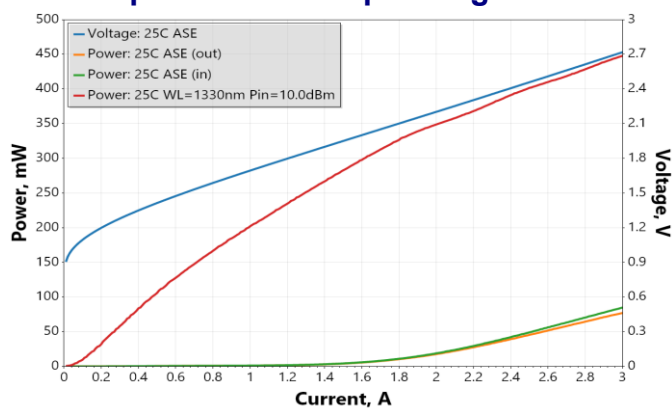
Parameter	Min.	Typ.	Max.	Unit
Output Power (each port)		15		mW
Forward Voltage		1.7	2.2	V
Mean Wavelength		1225		nm
Bandwidth (FWHM)		17		nm
Ripples* (RMS)		0.02	1	dB
Polarisation Extinction Ratio (PER)	13	16		dB
Polarization		TE		

* - measured in 1nm span around spectrum maximum with 20pm resolution.

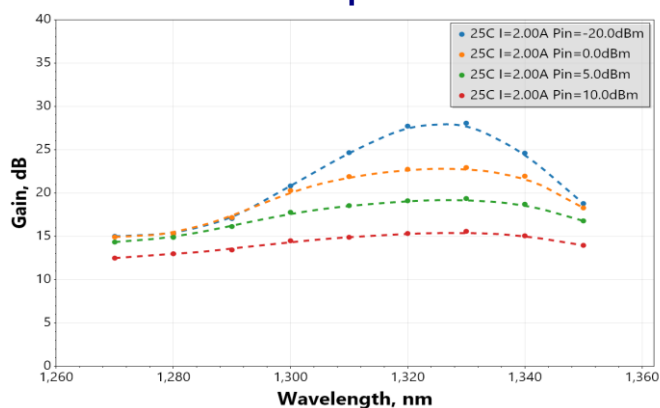
Typical Performance (for reference only)

@ CW, Tcase=25°C

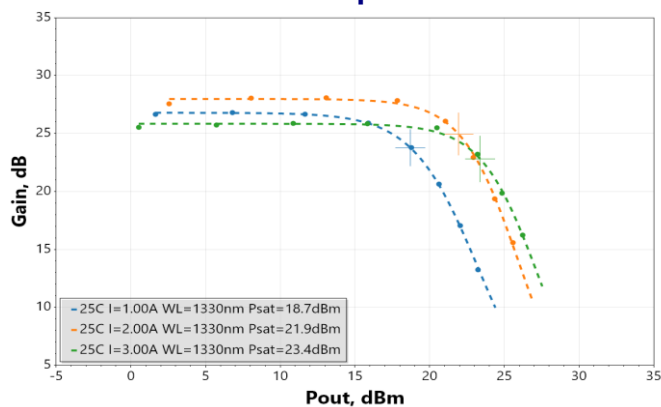
Output Power vs Operating Current



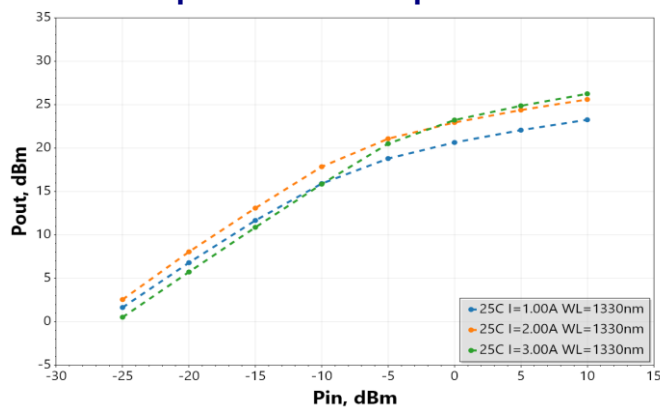
Gain Spectra



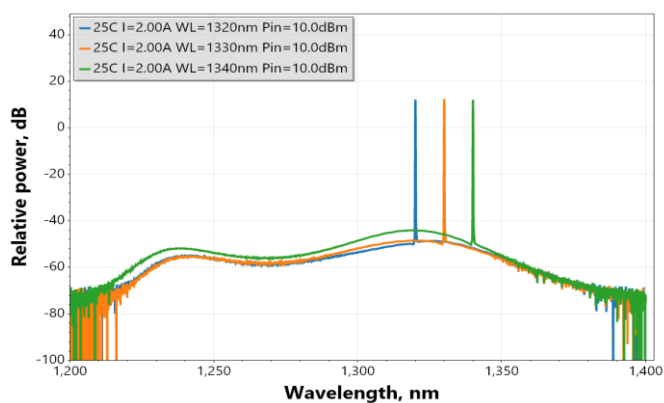
Gain vs Output Power



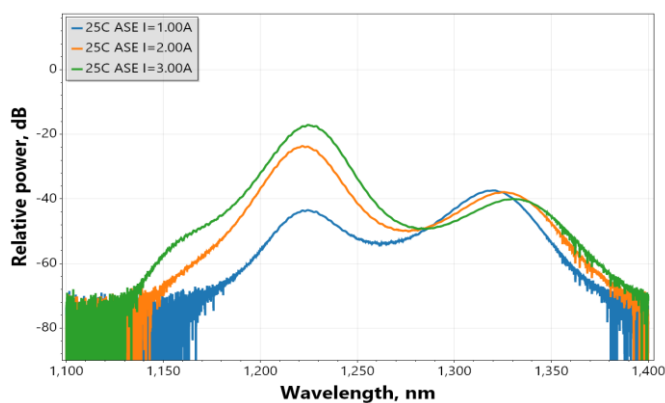
Output Power vs Input Power



Optical Spectra of Amplified Optical Signals



Optical Spectra (ASE)

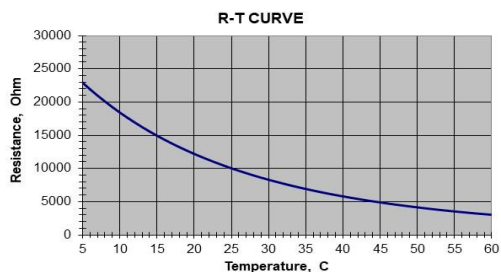


Absolute Maximum Ratings

Parameter	Min	Max	Unit
Output Optical Power		500	mW
Input Optical Power		20	dBm
Forward Current		3500	mA
Reverse Voltage		2	V
TEC Current		3	A
TEC Voltage		4	V
Chip Operating Temperature	5	50	°C
Case Operating Temperature	0	50	°C
Storage Temperature	0	50	°C
Pin Soldering Temperature (max 10 sec, max case temperature 120°C)		300	°C
Fiber Band Radius	3		cm

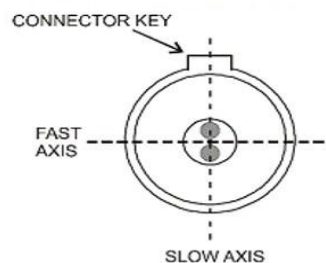
Thermistor specification

Parameters	Value	Unit
Type	NTC	
Resistance @ 25°C	10±0.1	kOhm
Beta 25-85°C	3435±1%	K



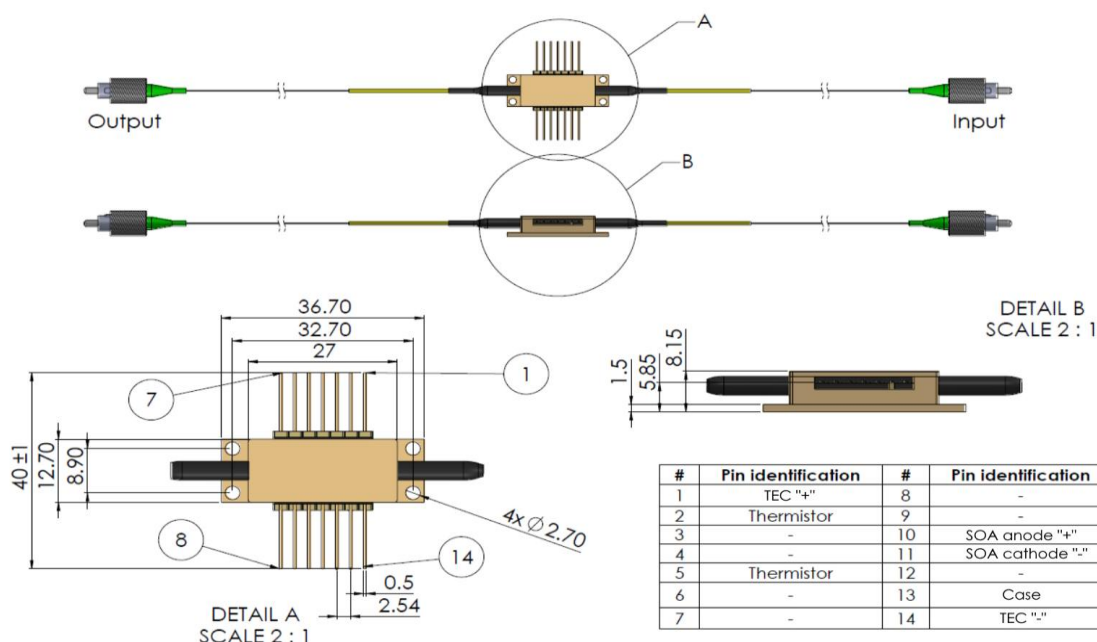
Fiber specification

Parameters	Value	Value	Unit
Fiber Type	HI1060	PM1310	
Numerical Aperture (Typical)	0.14	0.12	
Cut-off Wavelength	920±50	1200±70	nm
Mode-Field (core) Diameter	6.2±0.3 @1060nm	9.3±0.5 @1300nm	µm
Cladding Diameter	125±1	125±1	µm
Coating (buffer) Diameter	245±15	245±15	µm
Loose Tube Diameter (optional)	900	900	µm
Connector	FC/APC	FC/APC	
Key	narrow	narrow	



The output light is polarized along the slow axis of PM fiber.

Dimensions (in mm)



Safety and Operating Instructions

The light emitted from this device is invisible and can be harmful to the human eye. Avoid looking directly into the fiber connector when the device is in operation. Proper laser safety eyewear must be worn during operation with open connector.

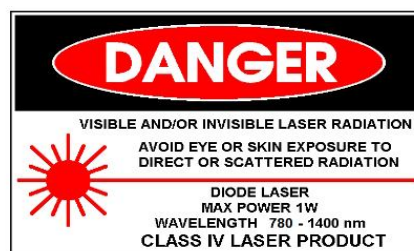
Absolute Maximum Ratings may be applied to the device for short period of time only. Exposure to maximum ratings for extended period of time or exposure to more than one maximum rating may cause damage or affect the reliability of the device. Operating the device outside of its maximum ratings may cause device failure or a safety hazard. Power supplies used with the component must be employed such that the maximum forward current cannot be exceeded.

A proper heatsink for the device on thermal radiator is required. The device must be mounted on radiator with 4 screws (bolt down in X-style fashion with initial torque set to 0.075Nm and final X-style bolt down at 0.15Nm) and with clamps. The deviation from flatness of radiator surface must be less than 0.05mm. It's recommended using of Indium foil or thermal conductive and soft material between bottom of the case and heatsink for thermal interface. It's undesirable to use thermal grease for this.

It is highly recommended to use a mount with additional temperature stabilization for the module's case. Even short-term exceeding of the Case Operating Temperature during operation can cause damage to the device.

Avoid back reflection to the device. It may give impact on the device performance in aspects of spectrum and power stability. It also may cause fatal facet damage. Using of optical isolators is highly recommended to block back reflection. Do not pull the fiber. Do not bend a fiber with a radius smaller than 3 cm. Fiber tip should always be protected from any contamination or damage during the process of installation. After removing the dust-preventing cap covered at fiber tip, carefully clean fiber tip by wiping through one direction using optical lens cleaning paper or cotton swab dabbed with Iso-Propanol or Ethyl alcohol. Operate the device with clean fiber connector only.

ESD PROTECTION - Electrostatic discharge is the primary cause of unexpected product failure. Take extreme precaution to prevent ESD. During device installation, ESD protection has to be maintained - use wrist straps, grounded work surfaces and rigorous antistatic techniques when handling the product.



Part-number Identification

BOA1330070HI300MXXXX -> 300mW output power at 1330nm mean wavelength, 70nm bandwidth, HI1060 fiber
BOA1330070PM300MLXXX -> 300mW output power at 1330nm mean wavelength, 70nm bandwidth, PM1310 fiber, with loose tube

NOTE: Innolume product specifications are subject to change without notice